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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	64MHz
Connectivity	EBI/EMI, I²C, IrDA, Memory Card, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	79
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 15x10/12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TFBGA
Supplier Device Package	100-TFBGA (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsam3s8ca-cu

1. Description

The Atmel SAM3S8/SD8 series is a member of a family of Flash microcontrollers based on the high performance 32-bit ARM Cortex-M3 RISC processor. It operates at a maximum speed of 64 MHz and features up to 512 Kbytes of Flash (dual plane on SAM3SD8) and up to 64 Kbytes of SRAM. The peripheral set includes a Full Speed USB Device port with embedded transceiver, a High Speed MCI for SDIO/SD/MMC, an External Bus Interface featuring a Static Memory Controller providing connection to SRAM, PSRAM, NOR Flash, LCD Module and NAND Flash, 2(3)x USARTs, (3 on SAM3SD8C) 2x UARTs, 2x TWIs, 3x SPI, an I2S, as well as 1 PWM timer, 6x general-purpose 16-bit timers (with stepper motor and quadrature decoder logic support), an RTC, a 12-bit ADC, a 12-bit DAC and an analog comparator.

The SAM3S8/SD8 series is ready for capacitive touch thanks to the QTouch® library, offering an easy way to implement buttons, wheels and sliders.

The SAM3S8/SD8 device is a medium range general purpose microcontroller with the best ratio in terms of reduced power consumption, processing power and peripheral set. This enables the SAM3S8/SD8 to sustain a wide range of applications including consumer, industrial control, and PC peripherals.

It operates from 1.62V to 3.6V and is available in 64- and 100-pin QFP, 64-pin QFN, and 100-pin BGA packages.

The SAM3S8/SD8 series is the ideal migration path from the SAM7S series for applications that require more performance. The SAM3S8/SD8 series is pin-to-pin compatible with the SAM7S series.

1.1 Configuration Summary

The SAM3S8/SD8 series devices differ in memory size, package and features. Table 1-1 summarizes the configurations of the device family.

Table 1-1. Configuration Summary

Feature	SAM3S8B	SAM3S8C	SAM3SD8B	SAM3SD8C
Flash	512 Kbytes	512 Kbytes	512 Kbytes	512 Kbytes
SRAM	64 Kbytes	64 Kbytes	64 Kbytes	64 Kbytes
Package	LQFP64 QFN64	LQFP100 BGA100	LQFP64 QFN64	LQFP100 BGA100
Number of PIOs	47	79	47	79
12-bit ADC	11 channels(2)	16 channels(2)	11 channels(2)	16 channels(2)
12-bit DAC	2 channels	2 channels	2 channels	2 channels
Timer Counter Channels	6	6	6	6
PDC Channels	22	22	24	24
USART/UART	2/2(1)	2/2(1)	2/2(1)	3/2(1)
HSMCI	1 port/4 bits	1 port/4 bits	1 port/4 bits	1 port/4 bits
External Bus Interface	-	8-bit data, 4 chip selects, 24-bit address	-	8-bit data, 4 chip selects, 24-bit address

Notes: 1. Full Modem support on USART1.
2. One channel is reserved for internal temperature sensor.

2. Block Diagram

Figure 2-1. SAM3S8/SD8 100-pin version Block Diagram

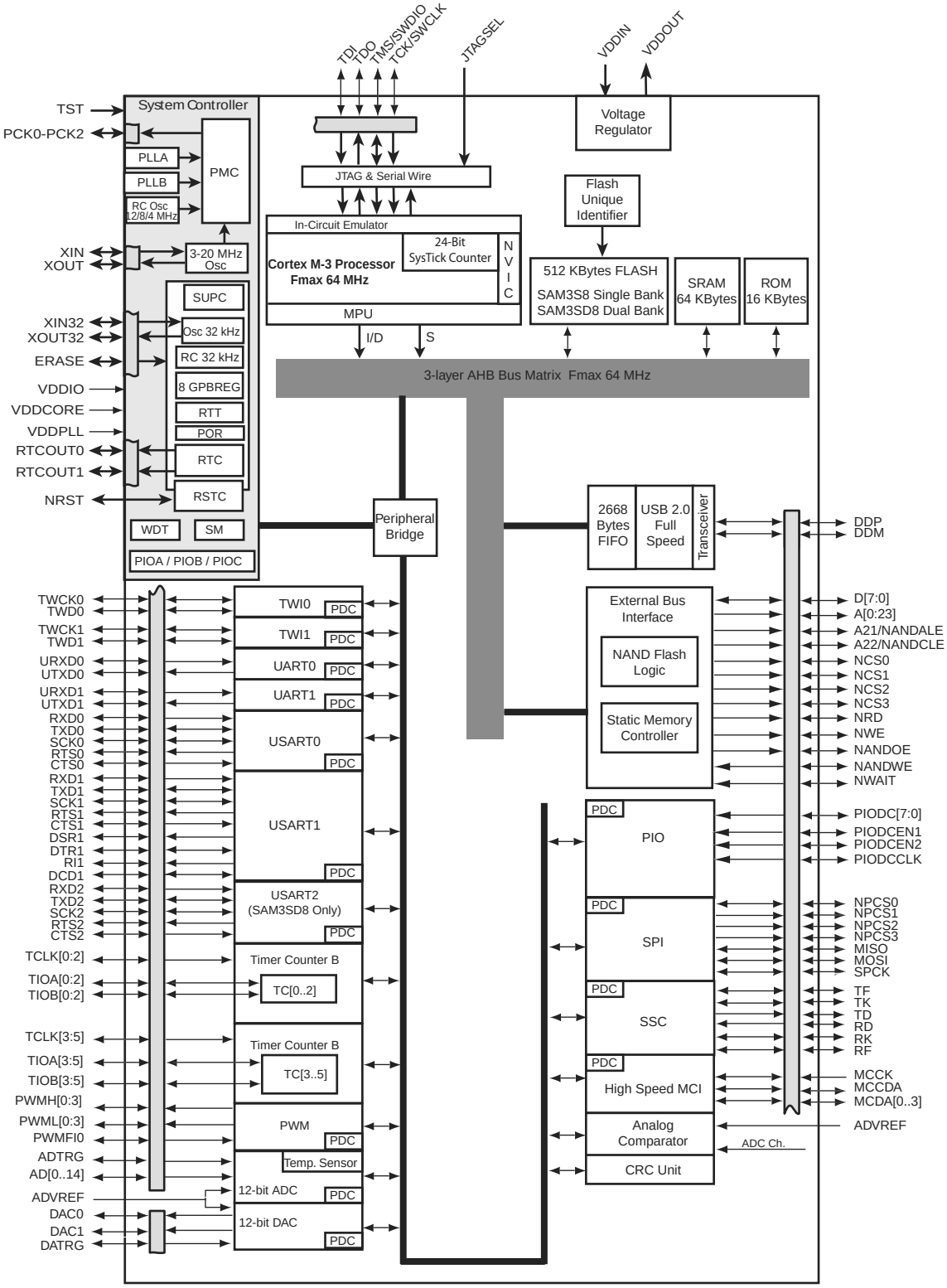


Table 3-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Voltage reference	Comments
Universal Synchronous Asynchronous Receiver Transmitter USARTx					
SCKx	USARTx Serial Clock	I/O			
TXDx	USARTx Transmit Data	I/O			
RXDx	USARTx Receive Data	Input			
RTSx	USARTx Request To Send	Output			
CTSx	USARTx Clear To Send	Input			
DTR1	USART1 Data Terminal Ready	I/O			
DSR1	USART1 Data Set Ready	Input			
DCD1	USART1 Data Carrier Detect	Output			
RI1	USART1 Ring Indicator	Input			
Synchronous Serial Controller - SSC					
TD	SSC Transmit Data	Output			
RD	SSC Receive Data	Input			
TK	SSC Transmit Clock	I/O			
RK	SSC Receive Clock	I/O			
TF	SSC Transmit Frame Sync	I/O			
RF	SSC Receive Frame Sync	I/O			
Timer/Counter - TC					
TCLKx	TC Channel x External Clock Input	Input			
TIOAx	TC Channel x I/O Line A	I/O			
TIOBx	TC Channel x I/O Line B	I/O			
Pulse Width Modulation Controller- PWMC					
PWMHx	PWM Waveform Output High for channel x	Output			
PWMLx	PWM Waveform Output Low for channel x	Output			only output in complementary mode when dead time insertion is enabled.
PWMFI0	**PWM Fault Input**	Input			
Serial Peripheral Interface - SPI					
MISO	Master In Slave Out	I/O			
MOSI	Master Out Slave In	I/O			
SPCK	SPI Serial Clock	I/O			
SPI_NPCS0	SPI Peripheral Chip Select 0	I/O	Low		
SPI_NPCS1 - SPI_NPCS3	SPI Peripheral Chip Select	Output	Low		

4.2.3 64-Lead LQFP and QFN Pinout

Table 4-3. 64-pin SAM3S8B/D8B pinout

1	ADVREF	17	GND	33	TDI/PB4	49	TDO/TRACESWO/ PB5
2	GND	18	VDDIO	34	PA6/PGMNOE	50	JTAGSEL
3	PB0/AD4	19	PA16/PGMD4	35	PA5/PGMRDY	51	TMS/SWDIO/PB6
4	PB1/AD5	20	PA15/PGMD3	36	PA4/PGMNCMD	52	PA31
5	PB2/AD6	21	PA14/PGMD2	37	PA27/PGMD15	53	TCK/SWCLK/PB7
6	PB3/AD7	22	PA13/PGMD1	38	PA28	54	VDDCORE
7	VDDIN	23	PA24/PGMD12	39	NRST	55	ERASE/PB12
8	VDDOUT	24	VDDCORE	40	TST	56	DDM/PB10
9	PA17/PGMD5/ AD*0*	25	PA25/PGMD13	41	PA29	57	DDP/PB11
10	PA18/PGMD6/ AD1	26	PA26/PGMD14	42	PA30	58	VDDIO
11	PA21/PGMD9/ AD8	27	PA12/PGMD0	43	PA3	59	PB13/DAC0
12	VDDCORE	28	PA11/PGMM3	44	PA2/PGMEN2	60	GND
13	PA19/PGMD7/ AD2	29	PA10/PGMM2	45	VDDIO	61	XOUT/PB8
14	PA22/PGMD10/ AD9	30	PA9/PGMM1	46	GND	62	XIN/PGMCK/PB9
15	PA23/PGMD11	31	PA8/*XOUT32*/ PGMM0	47	PA1/PGMEN1	63	PB14/DAC1
16	PA20/PGMD8/ AD3	32	PA7/*XIN32*/ PGMNVALID	48	PA0/PGMEN0	64	VDDPLL

Note: The bottom pad of the QFN package must be connected to ground.

- Supply Monitor alarm
- RTC alarm
- RTT alarm

5.5.2 Wait Mode

The purpose of the wait mode is to achieve very low power consumption while maintaining the whole device in a powered state for a startup time of less than 10 µs. Current Consumption in Wait mode is typically 15 µA (total current consumption) if the internal voltage regulator is used or 8 µA if an external regulator is used.

In this mode, the clocks of the core, peripherals and memories are stopped. However, the core, peripherals and memories power supplies are still powered. From this mode, a fast start up is available.

This mode is entered via Wait for Event (WFE) instructions with LPM = 1 (Low Power Mode bit in PMC_FSMR). The Cortex-M3 is able to handle external events or internal events in order to wake-up the core (WFE). This is done by configuring the external lines WUP0-15 as fast startup wake-up pins (refer to Section 5.7 “Fast Startup”). RTC or RTT Alarm and USB wake-up events can be used to wake up the CPU (exit from WFE).

Entering Wait Mode:

- Select the 4/8/12 MHz fast RC oscillator as Main Clock
- Set the LPM bit in the PMC Fast Startup Mode Register (PMC_FSMR)
- Execute the Wait-For-Event (WFE) instruction of the processor

Note: Internal Main clock resynchronization cycles are necessary between the writing of MOSCRCEN bit and the effective entry in Wait mode. Depending on the user application, waiting for MOSCRCEN bit to be cleared is recommended to ensure that the core will not execute undesired instructions.

5.5.3 Sleep Mode

The purpose of sleep mode is to optimize power consumption of the device versus response time. In this mode, only the core clock is stopped. The peripheral clocks can be enabled. The current consumption in this mode is application dependent.

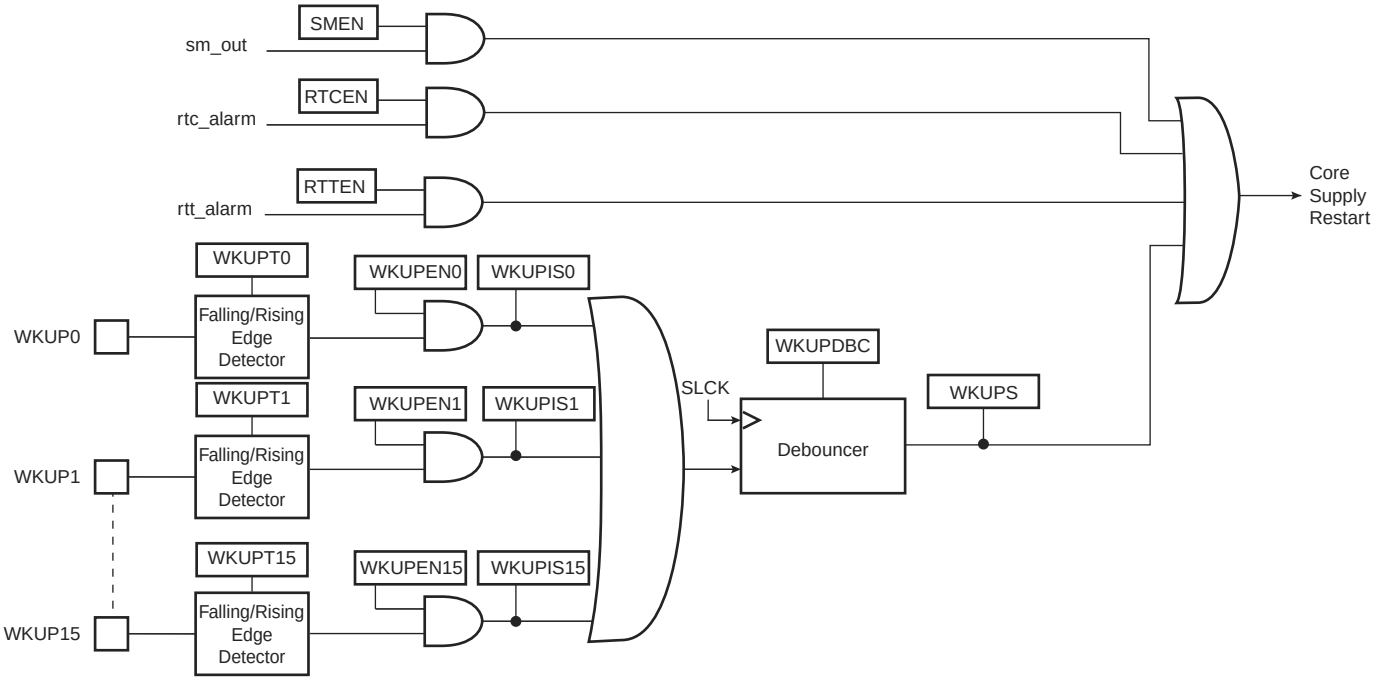
This mode is entered via Wait for Interrupt (WFI) or Wait for Event (WFE) instructions with LPM = 0 in PMC_FSMR.

The processor can be awakened from an interrupt if WFI instruction of the Cortex M3 is used, or from an event if the WFE instruction is used to enter this mode.

5.6 Wake-up Sources

The wake-up events allow the device to exit the backup mode. When a wake-up event is detected, the Supply Controller performs a sequence which automatically reenables the core power supply and the SRAM power supply, if they are not already enabled.

Figure 5-4. Wake-up Source



6.3 Test Pin

The TST pin is used for JTAG Boundary Scan Manufacturing Test or Fast Flash programming mode of the SAM3S8/SD8 series. The TST pin integrates a permanent pull-down resistor of about 15 kΩ to GND, so that it can be left unconnected for normal operations. To enter fast programming mode, see the Fast Flash Programming Interface (FFPI) section. For more on the manufacturing and test mode, refer to the “Debug and Test” section of the product datasheet.

6.4 NRST Pin

The NRST pin is bidirectional. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. It will reset the Core and the peripherals except the Backup region (RTC, RTT and Supply Controller). There is no constraint on the length of the reset pulse and the reset controller can guarantee a minimum pulse length. The NRST pin integrates a permanent pull-up resistor to VDDIO of about 100 kΩ. By default, the NRST pin is configured as an input.

6.5 ERASE Pin

The ERASE pin is used to reinitialize the Flash content (and some of its NVM bits) to an erased state (all bits read as logic level 1). It integrates a pull-down resistor of about 100 kΩ to GND, so that it can be left unconnected for normal operations.

This pin is debounced by SCLK to improve the glitch tolerance. When the ERASE pin is tied high during less than 100 ms, it is not taken into account. The pin must be tied high during more than 220 ms to perform a Flash erase operation.

The ERASE pin is a system I/O pin and can be used as a standard I/O. At startup, the ERASE pin is not configured as a PIO pin. If the ERASE pin is used as a standard I/O, startup level of this pin must be low to prevent unwanted erasing. Refer to Section 10.17 “Peripheral Signal Multiplexing on I/O Lines” on page 40. Also, if the ERASE pin is used as a standard I/O output, asserting the pin to low does not erase the Flash.

7. Processor and Architecture

7.1 ARM Cortex-M3 Processor

- Version 2.0
- Thumb-2 (ISA) subset consisting of all base Thumb-2 instructions, 16-bit and 32-bit.
- Harvard processor architecture enabling simultaneous instruction fetch with data load/store.
- Three-stage pipeline.
- Single cycle 32-bit multiply.
- Hardware divide.
- Thumb and Debug states.
- Handler and Thread modes.
- Low latency ISR entry and exit.

7.2 APB/AHB bridge

The SAM3S8/SD8 embeds One Peripheral bridge:

The peripherals of the bridge are clocked by MCK.

7.3 Matrix Masters

The Bus Matrix of the SAM3S8/SD8 manages 4 masters, which means that each master can perform an access concurrently with others, to an available slave.

Each master has its own decoder, which is defined specifically for each master. In order to simplify the addressing, all the masters have the same decodings.

Table 7-1. List of Bus Matrix Masters

Master 0	Cortex-M3 Instruction/Data
Master 1	Cortex-M3 System
Master 2	Peripheral DMA Controller (PDC)
Master 3	CRC Calculation Unit

7.4 Matrix Slaves

The Bus Matrix of the SAM3S8/SD8 manages 5 slaves. Each slave has its own arbiter, allowing a different arbitration per slave.

Table 7-2. List of Bus Matrix Slaves

Slave 0	Internal SRAM
Slave 1	Internal ROM
Slave 2	Internal Flash
Slave 3	External Bus Interface
Slave 4	Peripheral Bridge

7.5 Master to Slave Access

All the Masters can normally access all the Slaves. However, some paths do not make sense, for example allowing access from the Cortex-M3 S Bus to the Internal ROM. Thus, these paths are forbidden or simply not wired, and shown as “-” in the following table.

Table 7-3. SAM3S8_SD8 Master to Slave Access

Slaves	Masters	0	1	2	3
		Cortex-M3 I/D Bus	Cortex-M3 S Bus	PDC	CRCCU
0	Internal SRAM	-	X	X	X
1	Internal ROM	X	-	X	X
2	Internal Flash	X	-	-	X
3	External Bus Interface	-	X	X	X
4	Peripheral Bridge	-	X	X	-

7.6 Peripheral DMA Controller

- Handles data transfer between peripherals and memories
- Low bus arbitration overhead
  - One Master Clock cycle needed for a transfer from memory to peripheral
  - Two Master Clock cycles needed for a transfer from peripheral to memory
- Next Pointer management for reducing interrupt latency requirement

The Peripheral DMA Controller handles transfer requests from the channel according to the following priorities (Low to High priorities):

Table 7-4. Peripheral DMA Controller

Instance name	Channel T/R
USART2	Transmit
USART2	Receive
PWM	Transmit
TWI1	Transmit
TWI0	Transmit
UART1	Transmit
UART0	Transmit
USART1	Transmit
USART0	Transmit
DACC	Transmit
SPI	Transmit

9. Memories

9.1 Embedded Memories

9.1.1 Internal SRAM

The SAM3S8 device (512-Kbytes, single bank flash) embeds a total of 64-Kbytes high-speed SRAM.

The SAM3SD8 device (512-Kbytes, dual bank flash) embeds a total of 64-Kbytes high-speed SRAM.

The SRAM is accessible over System Cortex-M3 bus at address 0x2000 0000.

The SRAM is in the bit band region. The bit band alias region is from 0x2200 0000 and 0x23FF FFFF.

9.1.2 Internal ROM

The SAM3S8/SD8 embeds an Internal ROM, which contains the SAM Boot Assistant (SAM-BA®), In Application Programming routines (IAP) and Fast Flash Programming Interface (FFPI).

At any time, the ROM is mapped at address 0x0080 0000.

9.1.3 Embedded Flash

9.1.3.1 Flash Overview

The Flash of the SAM3S8 (512-Kbytes single bank flash) is organized in one bank of 2048 pages of 256 bytes.

The Flash of the SAM3SD8 (512-Kbytes, dual bank flash) is organized in two banks of 1024 pages of 256 bytes each.

The Flash contains a 128-byte write buffer, accessible through a 32-bit interface.

9.1.3.2 Flash Power Supply

The Flash is supplied by VDDCORE.

9.1.3.3 Enhanced Embedded Flash Controller

The Enhanced Embedded Flash Controller (EEFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped on the APB.

The Enhanced Embedded Flash Controller ensures the interface of the Flash block with the 32-bit internal bus. Its 128-bit wide memory interface increases performance.

The user can choose between high performance or lower current consumption by selecting either 128-bit or 64-bit access. It also manages the programming, erasing, locking and unlocking sequences of the Flash using a full set of commands.

One of the commands returns the embedded Flash descriptor definition that informs the system about the Flash organization, thus making the software generic.

9.2 External Memories

The SAM3S8/SD8 features one External Bus Interface to provide an interface to a wide range of external memories and to any parallel peripheral.

9.2.1 Static Memory Controller

- 16-Mbyte Address Space per Chip Select
- 8- bit Data Bus
- Word, Halfword, Byte Transfers
- Programmable Setup, Pulse And Hold Time for Read Signals per Chip Select
- Programmable Setup, Pulse And Hold Time for Write Signals per Chip Select
- Programmable Data Float Time per Chip Select
- External Wait Request
- Automatic Switch to Slow Clock Mode
- Asynchronous Read in Page Mode Supported: Page Size Ranges from 4 to 32 Bytes
- NAND Flash additional logic supporting NAND Flash with Multiplexed Data/Address buses
- Hardware Configurable number of chip selects from 1 to 4
- Programmable timing on a per chip select basis

10. System Controller

The System Controller is a set of peripherals, which allow handling of key elements of the system, such as power, resets, clocks, time, interrupts, watchdog, etc...

See the system controller block diagram in Figure 10-1 on page 32.

10.1 System Controller and Peripherals Mapping

Please refer to Section 8-1 “SAM3S8/SD8 Product Mapping” on page 27.

All the peripherals are in the bit band region and are mapped in the bit band alias region.

10.2 Power-on-Reset, Brownout and Supply Monitor

The SAM3S8/SD8 embeds three features to monitor, warn and/or reset the chip:

- Power-on-Reset on VDDIO
- Brownout Detector on VDDCORE
- Supply Monitor on VDDIO

10.2.1 Power-on-Reset

The Power-on-Reset monitors VDDIO. It is always activated and monitors voltage at start up but also during power down. If VDDIO goes below the threshold voltage, the entire chip is reset. For more information, refer to the Electrical Characteristics section of the datasheet.

10.2.2 Brownout Detector on VDDCORE

The Brownout Detector monitors VDDCORE. It is active by default. It can be deactivated by software through the Supply Controller (SUPC_MR). It is especially recommended to disable it during low-power modes such as wait or sleep modes.

If VDDCORE goes below the threshold voltage, the reset of the core is asserted. For more information, refer to the Supply Controller (SUPC) and Electrical Characteristics sections of the datasheet.

10.2.3 Supply Monitor on VDDIO

The Supply Monitor monitors VDDIO. It is not active by default. It can be activated by software and is fully programmable with 16 steps for the threshold (between 1.9V to 3.4V). It is controlled by the Supply Controller (SUPC). A sample mode is possible. It allows to divide the supply monitor power consumption by a factor of up to 2048. For more information, refer to the SUPC and Electrical Characteristics sections of the datasheet.

10.3 Reset Controller

The Reset Controller is based on a Power-on-Reset cell, and a Supply Monitor on VDDCORE.

The Reset Controller is capable to return to the software the source of the last reset, either a general reset, a wake-up reset, a software reset, a user reset or a watchdog reset.

The Reset Controller controls the internal resets of the system and the NRST pin input/output. It is capable to shape a reset signal for the external devices, simplifying to a minimum connection of a push-button on the NRST pin to implement a manual reset.

The configuration of the Reset Controller is saved as supplied on VDDIO.

10.4 Supply Controller (SUPC)

The Supply Controller controls the power supplies of each section of the processor and the peripherals (via Voltage regulator control)

The Supply Controller has its own reset circuitry and is clocked by the 32 kHz Slow clock generator.

The reset circuitry is based on a zero-power power-on reset cell and a brownout detector cell. The zero-power power-on reset allows the Supply Controller to start properly, while the software-programmable brownout detector allows detection of either a battery discharge or main voltage loss.

The Slow Clock generator is based on a 32 kHz crystal oscillator and an embedded 32 kHz RC oscillator. The Slow Clock defaults to the RC oscillator, but the software can enable the crystal oscillator and select it as the Slow Clock source.

The Supply Controller starts up the device by sequentially enabling the internal power switches and the Voltage Regulator, then it generates the proper reset signals to the core power supply.

It also enables to set the system in different low-power modes and to wake it up from a wide range of events.

10.5 Clock Generator

The Clock Generator is made up of:

- One Low-power 32768Hz Slow Clock Oscillator with bypass mode
- One Low-power RC Oscillator
- One 3-20 MHz Crystal Oscillator, which can be bypassed
- One Fast RC Oscillator, factory programmed. Three output frequencies can be selected: 4, 8 or 12 MHz. By default 4 MHz is selected.
- One 60 to 130 MHz PLL (PLLB) providing a clock for the USB Full Speed Controller
- One 60 to 130 MHz programmable PLL (PLLA), provides the clock, MCK to the processor and peripherals. The PLLA input frequency is from 3.5 MHz to 20 MHz.

10.9 Real-Time Timer

- Real-Time Timer, allowing backup of time with different accuracies
  - 32-bit Free-running backup Counter
  - Integrates a 16-bit programmable prescaler running on slow clock
  - Alarm Register capable to generate a wake-up of the system through the Shut Down Controller

10.10 Real Time Clock

- Low power consumption
- Full asynchronous design
- Two hundred year Gregorian and Persian calendar
- Programmable Periodic Interrupt
- Trimmable 32.7682 kHz crystal oscillator clock source
- Alarm and update parallel load
- Control of alarm and update Time/Calendar Data In
- Waveform output capability on GPIO pins in low power modes

10.11 General-Purpose Backed-up Registers

- Eight 32-bit backup general-purpose registers

10.12 Nested Vectored Interrupt Controller

- Thirty maskable external interrupts
- Sixteen priority levels
- Processor state automatically saved on interrupt entry, and restored on
- Dynamic reprioritizing of interrupts
- Priority grouping.
  - selection of pre-empting interrupt levels and non pre-empting interrupt levels.
- Support for tail-chaining and late arrival of interrupts.
  - back-to-back interrupt processing without the overhead of state saving and restoration between interrupts.
- Processor state automatically saved on interrupt entry, and restored on interrupt exit, with no instruction overhead.

10.17.2 PIO Controller B Multiplexing

Table 10-5. Multiplexing on PIO Controller B (PIOB)

I/O Line	Peripheral A	Peripheral B	Peripheral C	Extra Function	System Function	Comments
PB0	PWMH0			AD4/RTCOUT0		
PB1	PWMH1			AD5/RTCOUT1		
PB2	URXD1	NPCS2		AD6/WKUP12		
PB3	UTXD1	PCK2		AD7		
PB4	TWD1	PWMH2			TDI	
PB5	TWCK1	PWML0		WKUP13	TDO/TRACESWO	
PB6					TMS/SWDIO	
PB7					TCK/SWCLK	
PB8					XOUT	
PB9					XIN	
PB10					DDM	
PB11					DDP	
PB12	PWML1				ERASE	
PB13	PWML2	PCK0		DAC0		64/00 pins versions
PB14	NPCS1	PWMH3		DAC1		64/100 pins versions

10.17.3 PIO Controller C Multiplexing

Table 10-6. Multiplexing on PIO Controller C (PIOC)

I/O Line	Peripheral A	Peripheral B	Peripheral C	Extra Function	System Function	Comments
PC0	D0	PWML0				100 pin version
PC1	D1	PWML1				100 pin version
PC2	D2	PWML2				100 pin version
PC3	D3	PWML3				100 pin version
PC4	D4	NPCS1				100 pin version
PC5	D5					100 pin version
PC6	D6					100 pin version
PC7	D7					100 pin version
PC8	NWE					100 pin version
PC9	NANDOE	RXD2(1)				100 pin version
PC10	NANDWE	TXD2(1)				100 pin version
PC11	NRD					100 pin version
PC12	NCS3			AD12		100 pin version
PC13	NWAIT	PWML0		AD10		100 pin version
PC14	NCS0	SCK2(1)				100 pin version
PC15	NCS1	PWML1		AD11		100 pin version
PC16	A21/NANDALE	RTS2(1)				100 pin version
PC17	A22/NANDCLE	CTS2(1)				100 pin version
PC18	A0	PWMH0				100 pin version
PC19	A1	PWMH1				100 pin version
PC20	A2	PWMH2				100 pin version
PC21	A3	PWMH3				100 pin version
PC22	A4	PWML3				100 pin version
PC23	A5	TIOA3				100 pin version
PC24	A6	TIOB3				100 pin version
PC25	A7	TCLK3				100 pin version
PC26	A8	TIOA4				100 pin version
PC27	A9	TIOB4				100 pin version
PC28	A10	TCLK4				100 pin version
PC29	A11	TIOA5		AD13		100 pin version
PC30	A12	TIOB5		AD14		100 pin version
PC31	A13	TCLK5				100 pin version

Note: 1. USART2 only on SAM3SD8 in 100 pin package.

- Single ended/differential conversion
- Programmable gain: 1, 2, 4

11.11 Digital-to-Analog Converter (DAC)

- Up to 2 channel 12-bit DAC
- Up to 2 mega-samples conversion rate in single channel mode
- Flexible conversion range
- Multiple trigger sources for each channel
- 2 Sample/Hold (S/H) outputs
- Built-in offset and gain calibration
- Possible to drive output to ground
- Possible to use as input to analog comparator or ADC (as an internal wire and without S/H stage)
- Two PDC channels
- Power reduction mode

11.12 Static Memory Controller

- 16-Mbyte Address Space per Chip Select
- 8- bit Data Bus
- Word, Halfword, Byte Transfers
- Byte Write or Byte Select Lines
- Programmable Setup, Pulse And Hold Time for Read Signals per Chip Select
- Programmable Setup, Pulse And Hold Time for Write Signals per Chip Select
- Programmable Data Float Time per Chip Select
- Compliant with LCD Module
- External Wait Request
- Automatic Switch to Slow Clock Mode
- Asynchronous Read in Page Mode Supported: Page Size Ranges from 4 to 32 Bytes
- NAND Flash additional logic supporting NAND Flash with Multiplexed Data/Address buses
- Hardware Configurable number of chip select from 1 to 4
- Programmable timing on a per chip select basis

11.13 Analog Comparator

- One analog comparator
- High speed option vs. low-power option
  - 170 µA/xx ns active current consumption/propagation delay
  - 20 µA/xx ns active current consumption/propagation delay
- Selectable input hysteresis
  - 0, 20 mV, 50 mV
- Minus input selection:
  - DAC outputs

  - Temperature Sensor
  - ADVREF
  - AD0 to AD3 ADC channels
- Plus input selection:
  - All analog inputs
- output selection:
  - Internal signal
  - external pin
  - selectable inverter
- window function
- Interrupt on:
  - Rising edge, Falling edge, toggle
  - Signal above/below window, signal inside/outside window

11.14 Cyclic Redundancy Check Calculation Unit (CRCCU)

- 32-bit cyclic redundancy check automatic calculation
- CRC calculation between two addresses of the memory

Figure 12-3. 64-lead LQFP Package Mechanical Drawing

Table 12-1. 64-lead LQFP Package Dimensions (in mm)

Symbol	Millimeter			Inch		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	–	–	1.60	–	–	0.063
A1	0.05	–	0.15	0.002	–	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	12.00 BSC			0.472 BSC		
D1	10.00 BSC			0.383 BSC		
E	12.00 BSC			0.472 BSC		
E1	10.00 BSC			0.383 BSC		
R2	0.08	–	0.20	0.003	–	0.008
R1	0.08	–	–	0.003	–	–
q	0°	3.5°	7°	0°	3.5°	7°
θ_1	0°	–	–	0°	–	–
θ_2	11°	12°	13°	11°	12°	13°
θ_3	11°	12°	13°	11°	12°	13°
c	0.09	–	0.20	0.004	–	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		

13. Ordering Information

Table 13-1. Ordering Codes for SAM3S8/SD8 Devices

Ordering Code	MRL	Flash (Kbytes)	Package (Kbytes)	Package Type	Temperature Operating Range
ATSAM3S8CA-AU	A	512	QFP100	Green	Industrial -40°C to 85°C
ATSAM3S8CA-CU	A	512	BGA100	Green	Industrial -40°C to 85°C
ATSAM3S8BA-AU	A	512	QFP64	Green	Industrial -40°C to 85°C
ATSAM3S8BA-MU	A	512	QFN64	Green	Industrial -40°C to 85°C
ATSAM3SD8CA-AU	A	512	QFP100	Green	Industrial -40°C to 85°C
ATSAM3SD8CA-CU	A	512	BGA100	Green	Industrial -40°C to 85°C
ATSAM3SD8BA-AU	A	512	QFP64	Green	Industrial -40°C to 85°C
ATSAM3SD8BA-MU	A	512	QFN64	Green	Industrial -40°C to 85°C